Single Event Testing on Complex Devices: Test Like You Fly versus Test-Specific Design Structures

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Acronyms

• Block random access memory (BRAM)
• Combinatorial logic (CL)
• Device under test (DUT)
• Edge-triggered flip-flops (DFFs)
• Field programmable gate array (FPGA)
• Input – output (I/O)
• Linear energy transfer (LET)
• Low cost digital tester (LCDT)
• Probability of logic masking ($P_{\text{logic}}$)
• Radiation Effects and Analysis Group (REAG)
• Single event transient (SET)
• Single event upset (SEU)
• Single event upset cross-section ($\sigma_{\text{SEU}}$)
• Space Environment Information System (SPENVIS)
• Static random access memory (SRAM)
Abstract

• We present a mechanism for evaluating complex digital systems targeted for harsh radiation environments such as space.

• Focus is limited to analyzing the single event upset (SEU) susceptibility of designs implemented inside Field Programmable Gate Array (FPGA) devices.

• Tradeoffs are provided between application-specific versus test-specific test structures.
Goals of Single Event Upset Testing (1)

Error Rates

• Calculating SEU-error-rates based off of SEU cross sections ($\sigma_{SEUs}$).
  
  - $\sigma_{SEUs}$ are calculated by counting the number of DUT malfunctions given the number of particles the DUT is exposed to per LET.
  
  - SEU-error-rates are calculated by curve fitting $\sigma_{SEUs}$ and inputting this information into tools such as SPENVIS.
Goals of Single Event Upset Testing (2)

Error Responses

• In complex designs, error responses will vary:
  – Depends on what circuitry is hit:
    • Clock or reset global routes.
    • Dormant versus highly-active circuits.
  – Depends on which state the design is operating in when the SEU occurs:
    • Various states can invoke different error responses.
  – Depends at what portion of the clock-cycle the SEU occurs:
    • Some upsets may not get caught because of when in the clock-cycle the upset occurs.
    • If the upset temporarily disturbs the data input of a DFF close to a clock edge, metastability can occur.
Difference between Test Structure and Application-Specific Design

• Test structure is a design implemented in a DUT that is created specifically for SEU testing

• Application-specific design is circuitry implemented in a DUT that is either the final design targeted for space or a subset of the final design.
Test Structures versus Final Designs

• Although error rates and error responses are design dependent, useful information can be extrapolated from test structures versus the final design.

• Why use test structures versus final designs?
  – By the time the final design is complete, it is usually too late to perform radiation testing on it.
  – Can be too difficult to apply input stimuli to a final design.
  – Can be too difficult to monitor DUT responses.

The following slides give more insight into the benefits of using test structures versus full designs during radiation testing.
Best Practice for Radiation Testing: Logic Replication for Statistics

<table>
<thead>
<tr>
<th>Best-Practice for DUT Test Structure Development</th>
<th>How Application-Specific Test Structures Violate Best-Practice Considerations</th>
</tr>
</thead>
</table>
| Test structures should contain a large number of replicated logic in order to increase statistics: e.g., shift-registers with thousands of stages. | • Statistics are poor because usually there is not a significant amount of replication.  
• In addition, trends for specific elements are not able to be clearly identified/established. |

Example of replicating circuits for statistical purposes: DUT containing hundreds of counters versus 1 counter.
## Best Practice for Radiation Testing: State Space Traversal

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<tbody>
<tr>
<td>A test structure’s state space should be traversable such that it can be covered within one radiation test run.</td>
<td>The state space of a complex design cannot be traversed within one radiation test run.</td>
</tr>
<tr>
<td></td>
<td>Hence, a significant amount of circuitry and system states are not tested.</td>
</tr>
<tr>
<td></td>
<td>The result is SEU data that are uncharacteristic of the design.</td>
</tr>
</tbody>
</table>
## Best Practice for Radiation Testing: Logic Masking

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<tr>
<td>Logic masking should be minimized or controllable.</td>
<td>Application-specific test structures contain a significantly higher number of masked data paths than test structures.</td>
</tr>
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</table>

\[ P_{\text{logic}} \text{ is the probability that an upset will be masked from being captured by the system.} \]

\[ P_{\text{logic}} = 0 : \text{path is 100\% masked} \]

\[ P_{\text{logic}} = 1 : \text{path has no masking} \]
# Best Practice for Radiation Testing: Avoiding Unrealistic SEU Accumulation

## Best-Practice characteristics of a DUT design

### How Application-Specific Test Structures Violate Best-Practice Considerations

<table>
<thead>
<tr>
<th>Avoid unrealistic SEU accumulation from accelerated testing:</th>
<th>Application-specific test structures take up most of the DUT’s area. There are a lot of co-dependencies between logic. Hence, it is difficult to control SEU accumulation in an accelerated test environment.</th>
</tr>
</thead>
<tbody>
<tr>
<td>• Scrubbing (correcting) SEUs. Mostly performed on internal memories structures.</td>
<td></td>
</tr>
<tr>
<td>• Flush through test structures; e.g., shift-registers.</td>
<td></td>
</tr>
<tr>
<td>• Small number of gates per sub-test structure; e.g., testing hundreds of counters.</td>
<td></td>
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</tbody>
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# Best Practice for Radiation Testing: Increasing Visibility

## Best-Practice characteristics of a DUT design vs. How Application-Specific Test Structures Violate Best-Practice Considerations

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<tr>
<td>All (or a significant percentage of) potential upsets should be observable during testing.</td>
<td>A significant number of upsets in a complex design are generally not observable during radiation testing.</td>
</tr>
<tr>
<td>Test structures can easily be designed to enhance observable nodes; e.g., shift-registers and counters.</td>
<td>This is true mostly because of logic masking, limitations in state space traversal, limitations in I/O count, or time of upset propagation to observable nodes.</td>
</tr>
</tbody>
</table>
Testing Application Specific Designs

• The benefit of testing application specific designs is the ability to observe error responses specific to the application.

• However, the user must be aware of the following:
  – Unrealistic SEU accumulation in an accelerated environment.
  – Limited visibility due to masking and fractional state space traversal.
  – Poor statistics due to the variance in design circuits.

• $\sigma_{SEU}$s will most likely have a large variance if circuits are not able to be isolated and controlled.
Case Study

- DUT is a Xilinx V5QV – radiation hardened FPGA
- Application Specific Test Structure is an embedded microprocessor (Micro-blaze™).
- Goal is to determine error rates for using an embedded Micro-blaze™ processor in the Xilinx V5QV with and without cache.
  - Question: Does using cache in embedded memory increase the $\sigma_{SEU}$s such that the Micro-blaze™ will not meet project requirements?
Suggestions on How to Test the Application Specific Design

• Because the goal is to study caching SEU effects, use a test design that contains cache and one that does not.

• Test basic structures such as shift-registers and counters to get an underlying understanding of device SEU characteristics.

• Basic test-structure analysis characterizes:
  – Sequential memory elements (DFFs)
  – Combinatorial logic (CL)
  – Global routes

• Increase visibility of the Micro-blaze™ during testing
Increasing Visibility

• When testing application-specific designs, there are areas where visibility will be limited and cannot be increased.
  – This is why we also test basic test structures, such as shift registers and counters.
  – From test data, we extrapolate $\sigma_{\text{SEU}}$ information to fit the application specific design.
  – Data extrapolation has been performed for this case study, but is beyond the scope of this presentation.

• Because visibility is limited, it is important to have the ability to differentiate between upsets. Performed by:
  – Supporting test structures,
  – Supporting test equipment,
  – Data post processing, or
  – Understanding the internal structures of the DUT
Processor and SRAM Communication

SRAM: Static random access memory
BRAM: Block random access memory

- **Processors talk to memory**

- **Most processor radiation tests detect errors by erroneous SRAM memory writes**

- **Visibility is significantly limited**

- **We increase visibility by replacing external SRAM with the REAG low-cost digital Tester (LCDT)**
More on Increasing Visibility with Microprocessor Testing (1)

• As previously stated, the embedded SRAM in the tester (BRAM) takes the place of normal memory accesses.

• In addition, each memory access is time stamped and logged in an alternate bank of BRAM. Only the last 512 accesses are kept.

• After each test run, the time-stamped logs are output to the user.

```
Timestamp  WR  ADDR  DATA
```

Write  Read  Address
More on Increasing Visibility with Microprocessor Testing (2)

Halted  
Error  
Trace Instruction  
Trace Valid Instruction  
Trace Exception Taken  
Trace Exception Kind  
Trace Register Write  
Trace Register Address  
Trace Data cache Request  
Trace Data cache Hit  
Trace Data cache Ready  
Trace Data cache Read  
Trace Instruction cache Request  
Trace Instruction cache Hit

DUT: device under test

TESTER

Watchdogs

Send watchdog errors to host PC

Summary of Case Study Test Enhancements

- Visibility was increased by isolating memory accesses as follows:
  - Moving the instruction and data storage to the LCDT for traffic observation.
  - Performing tests with and without cache to determine the influence cache has on upsets.

- Differentiating global upsets from the normal data set:
  - Helped to understand which upsets are prominent.
  - Gave insight on how the use of cache will affect \( \sigma_{SEUs} \).

- Monitoring internal Micro-blaze™ signals
  - \( \sigma_{SEUs} \) are not reliant on detecting erroneous memory read and writes anymore. Data are too limited and uninformative with sole reliance on memory reads and writes.
  - Can now determine when a processor crashes and how.
Comparing Micro-blaze™ $\sigma_{SEU}$s and Global Clock $\sigma_{SEU}$s

SEU Cross Sections:
Cache vs. No Cache with Global Routes

![Graph showing SEU cross sections for Cache vs. No Cache with Global Routes](image-url)

- Configuration 6: Cache
- Configuration 5: No Cache
- Global Routes

Summary

• We presented a framework for evaluating complex digital systems targeted for harsh radiation environments, such as space.

• Tradeoffs are provided between application-specific versus test-specific test structures.

• If performing accelerated radiation testing on an application specific design:
  – Understand limitations in data,
  – Be prepared for complex data de-convolution,
  – Pay attention to global structures, and
  – Use basic-test structures to obtain an underlying understanding of DUT SEU behavior.